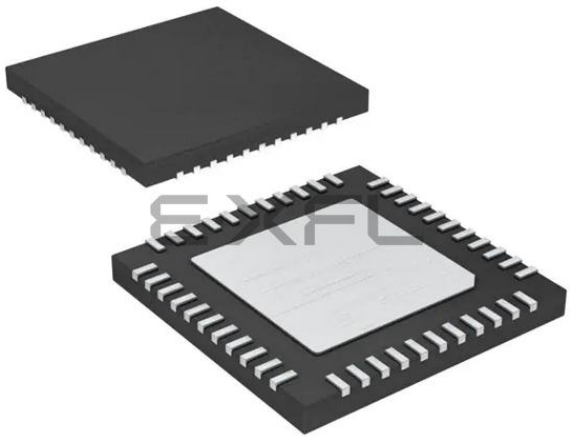

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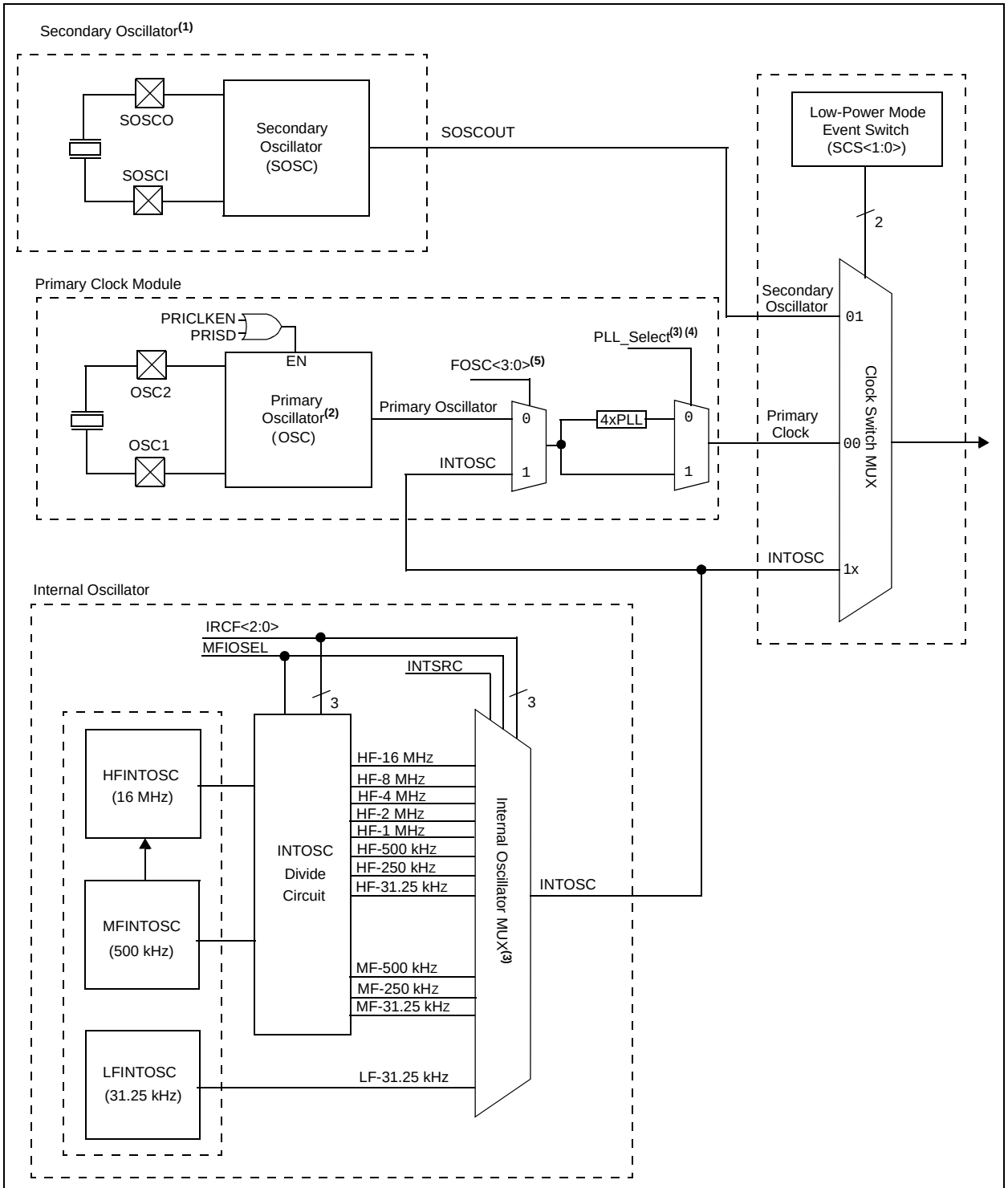
Details	
Product Status	Active
Core Processor	PIC
Core Size	8-Bit
Speed	64MHz
Connectivity	I²C, SPI, UART/USART
Peripherals	Brown-out Detect/Reset, HLVD, POR, PWM, WDT
Number of I/O	35
Program Memory Size	8KB (4K x 16)
Program Memory Type	FLASH
EEPROM Size	256 x 8
RAM Size	512 x 8
Voltage - Supply (Vcc/Vdd)	2.3V ~ 5.5V
Data Converters	A/D 30x10b
Oscillator Type	Internal
Operating Temperature	-40°C ~ 85°C (TA)
Mounting Type	Surface Mount
Package / Case	44-VQFN Exposed Pad
Supplier Device Package	44-QFN (8x8)
Purchase URL	https://www.e-xfl.com/product-detail/microchip-technology/pic18f43k22-i-ml

TABLE 3: PIC18(L)F4XK22 PIN SUMMARY

40-PDIP	40-UQFN	44-TQFP	44-QFN	I/O	Analog	Comparator	CTMU	SR Latch	Reference	(E)CCP	EUSART	MSSP	Timers	Interrupts	Pull-up	Basic
2	17	19	19	RA0	AN0	C12IN0-										
3	18	20	20	RA1	AN1	C12IN1-										
4	19	21	21	RA2	AN2	C2IN+			VREF- DACOUT							
5	20	22	22	RA3	AN3	C1IN+			VREF+							
6	21	23	23	RA4		C1OUT		SRQ					T0CKI			
7	22	24	24	RA5	AN4	C2OUT		SRNQ	HLVDIN			$\overline{SS}$1				
14	29	31	33	RA6												OSC2 CLKO
13	28	30	32	RA7												OSC1 CLKI
33	8	8	9	RB0	AN12			SRI		FLT0				INT0	Y	
34	9	9	10	RB1	AN10	C12IN3-								INT1	Y	
35	10	10	11	RB2	AN8		CTED1							INT2	Y	
36	11	11	12	RB3	AN9	C12IN2-	CTED2			CCP2 P2A(1)					Y	
37	12	14	14	RB4	AN11								T5G	IOC	Y	
38	13	15	15	RB5	AN13					CCP3 P3A(3)			T1G T3CKI(2)	IOC	Y	
39	14	16	16	RB6										IOC	Y	PGC
40	15	17	17	RB7										IOC	Y	PGD
15	30	32	34	RC0						P2B(4)			SOSCO T1CKI T3CKI(2) T3G			
16	31	35	35	RC1						CCP2(1) P2A			SOSCI			
17	32	36	36	RC2	AN14		CTPLS			CCP1 P1A			T5CKI			
18	33	37	37	RC3	AN15							SCK1 SCL1				
23	38	42	42	RC4	AN16							SDI1 SDA1				
24	39	43	43	RC5	AN17							SDO1				
25	40	44	44	RC6	AN18						TX1 CK1					
26	1	1	1	RC7	AN19						RX1 DT1					
19	34	38	38	RD0	AN20							SCK2 SCL2				
20	35	39	39	RD1	AN21					CCP4		SDI2 SDA2				
21	36	40	40	RD2	AN22					P2B(4)						
22	37	41	41	RD3	AN23					P2C		$\overline{SS}$2				
27	2	2	2	RD4	AN24					P2D		SD02				
28	3	3	3	RD5	AN25					P1B						
29	4	4	4	RD6	AN26					P1C	TX2 CK2					
30	5	5	5	RD7	AN27					P1D	RX2 DT2					
8	23	25	25	RE0	AN5					CCP3 P3A(3)						

Note 1: CCP2 multiplexed in fuses.
2: T3CKI multiplexed in fuses.
3: CCP3/P3A multiplexed in fuses.
4: P2B multiplexed in fuses.

FIGURE 2-1: SIMPLIFIED OSCILLATOR SYSTEM BLOCK DIAGRAM



Note 1: Details in Figure 2-4.

2: Details in Figure 2-2.

3: Details in Figure 2-3.

4: Details in Table 2-1.

5: The Primary Oscillator MUX uses the INTOSC branch when FOSC<3:0> = 100x.

The Stack Pointer is readable and writable and the address on the top of the stack is readable and writable through the Top-of-Stack (TOS) Special File Registers. Data can also be pushed to, or popped from the stack, using these registers.

A CALL type instruction causes a push onto the stack; the Stack Pointer is first incremented and the location pointed to by the Stack Pointer is written with the contents of the PC (already pointing to the instruction following the CALL). A RETURN type instruction causes a pop from the stack; the contents of the location pointed to by the STKPTR are transferred to the PC and then the Stack Pointer is decremented.

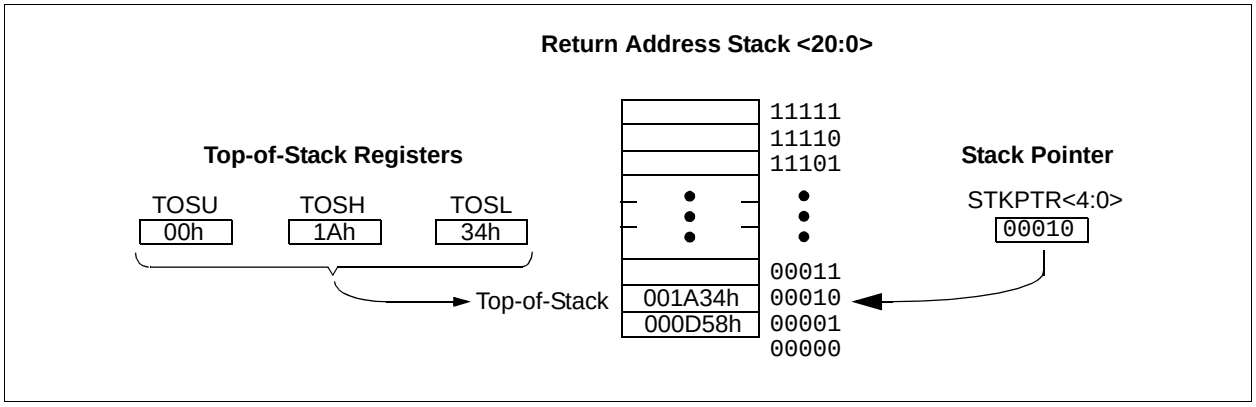
The Stack Pointer is initialized to '00000' after all Resets. There is no RAM associated with the location corresponding to a Stack Pointer value of '00000'; this is only a Reset value. Status bits indicate if the stack is full or has overflowed or has underflowed.

5.1.2.1 Top-of-Stack Access

Only the top of the return address stack (TOS) is readable and writable. A set of three registers, TOSU:TOSH:TOSL, hold the contents of the stack location pointed to by the STKPTR register (Figure 5-2). This allows users to implement a software stack if necessary. After a CALL, RCALL or interrupt, the software can read the pushed value by reading the TOSU:TOSH:TOSL registers. These values can be placed on a user defined software stack. At return time, the software can return these values to TOSU:TOSH:TOSL and do a return.

The user must disable the Global Interrupt Enable (GIE) bits while accessing the stack to prevent inadvertent stack corruption.

FIGURE 5-2: RETURN ADDRESS STACK AND ASSOCIATED REGISTERS



5.1.2.2 Return Stack Pointer (STKPTR)

The STKPTR register (Register 5-1) contains the Stack Pointer value, the STKFUL (stack full) Status bit and the STKUNF (Stack Underflow) Status bits. The value of the Stack Pointer can be 0 through 31. The Stack Pointer increments before values are pushed onto the stack and decrements after values are popped off the stack. On Reset, the Stack Pointer value will be zero. The user may read and write the Stack Pointer value. This feature can be used by a Real-Time Operating System (RTOS) for return stack maintenance.

After the PC is pushed onto the stack 31 times (without popping any values off the stack), the STKFUL bit is set. The STKFUL bit is cleared by software or by a POR.

The action that takes place when the stack becomes full depends on the state of the STVREN (Stack Overflow Reset Enable) Configuration bit. (Refer to **Section 24.1 "Configuration Bits"** for a description of the device Configuration bits.) If STVREN is set (default), the 31st push will push the (PC + 2) value onto the stack, set the STKFUL bit and reset the device. The STKFUL bit will remain set and the Stack Pointer will be set to zero.

If STVREN is cleared, the STKFUL bit will be set on the 31st push and the Stack Pointer will increment to 31. Any additional pushes will not overwrite the 31st push and STKPTR will remain at 31.

When the stack has been popped enough times to unload the stack, the next pop will return a value of zero to the PC and sets the STKUNF bit, while the Stack Pointer remains at zero. The STKUNF bit will remain set until cleared by software or until a POR occurs.

Note:	Returning a value of zero to the PC on an underflow has the effect of vectoring the program to the Reset vector, where the stack conditions can be verified and appropriate actions can be taken. This is not the same as a Reset, as the contents of the SFRs are not affected.

TABLE 5-2: REGISTER FILE SUMMARY FOR PIC18(L)F2X/4XK22 DEVICES

Address	Name	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	Value on POR, BOR
FFFh	TOSU	—	—	—	Top-of-Stack, Upper Byte (TOS<20:16>)					---0 0000
FFEh	TOSH	Top-of-Stack, High Byte (TOS<15:8>)								0000 0000
FFDh	TOSL	Top-of-Stack, Low Byte (TOS<7:0>)								0000 0000
FFCh	STKPTR	STKFUL	STKUNF	—	STKPTR<4:0>					00-0 0000
FFBh	PCLATU	—	—	—	Holding Register for PC<20:16>					---0 0000
FFAh	PCLATH	Holding Register for PC<15:8>								0000 0000
FF9h	PCL	Holding Register for PC<7:0>								0000 0000
FF8h	TBLPTRU	—	—	Program Memory Table Pointer Upper Byte(TBLPTR<21:16>)						--00 0000
FF7h	TBLPTRH	Program Memory Table Pointer High Byte(TBLPTR<15:8>)								0000 0000
FF6h	TBLPTRL	Program Memory Table Pointer Low Byte(TBLPTR<7:0>)								0000 0000
FF5h	TABLAT	Program Memory Table Latch								0000 0000
FF4h	PRODH	Product Register, High Byte								xxxx xxxx
FF3h	PRODL	Product Register, Low Byte								xxxx xxxx
FF2h	INTCON	GIE/GIEH	PEIE/GIEL	TMR0IE	INT0IE	RBIE	TMR0IF	INT0IF	RBIF	0000 000x
FF1h	INTCON2	$\overline{\text{RBPU}}$	INTEDG0	INTEDG1	INTEDG2	—	TMR0IP	—	RBIP	1111 -1-1
FF0h	INTCON3	INT2IP	INT1IP	—	INT2IE	INT1IE	—	INT2IF	INT1IF	11-0 0-00
FEFh	INDF0	Uses contents of FSR0 to address data memory – value of FSR0 not changed (not a physical register)								---- ----
FEEh	POSTINC0	Uses contents of FSR0 to address data memory – value of FSR0 post-incremented (not a physical register)								---- ----
FEDh	POSTDEC0	Uses contents of FSR0 to address data memory – value of FSR0 post-decremented (not a physical register)								---- ----
FECh	PREINC0	Uses contents of FSR0 to address data memory – value of FSR0 pre-incremented (not a physical register)								---- ----
FEBh	PLUSW0	Uses contents of FSR0 to address data memory – value of FSR0 pre-incremented (not a physical register) – value of FSR0 offset by W								---- ----
FEAh	FSR0H	—	—	—	—	Indirect Data Memory Address Pointer 0, High Byte				---- 0000
FE9h	FSR0L	Indirect Data Memory Address Pointer 0, Low Byte								xxxx xxxx
FE8h	WREG	Working Register								xxxx xxxx
FE7h	INDF1	Uses contents of FSR1 to address data memory – value of FSR1 not changed (not a physical register)								---- ----
FE6h	POSTINC1	Uses contents of FSR1 to address data memory – value of FSR1 post-incremented (not a physical register)								---- ----
FE5h	POSTDEC1	Uses contents of FSR1 to address data memory – value of FSR1 post-decremented (not a physical register)								---- ----
FE4h	PREINC1	Uses contents of FSR1 to address data memory – value of FSR1 pre-incremented (not a physical register)								---- ----
FE3h	PLUSW1	Uses contents of FSR1 to address data memory – value of FSR1 pre-incremented (not a physical register) – value of FSR1 offset by W								---- ----
FE2h	FSR1H	—	—	—	—	Indirect Data Memory Address Pointer 1, High Byte				---- 0000
FE1h	FSR1L	Indirect Data Memory Address Pointer 1, Low Byte								xxxx xxxx
FE0h	BSR	—	—	—	—	Bank Select Register				---- 0000
FDFh	INDF2	Uses contents of FSR2 to address data memory – value of FSR2 not changed (not a physical register)								---- ----
FDEh	POSTINC2	Uses contents of FSR2 to address data memory – value of FSR2 post-incremented (not a physical register)								---- ----
FDDh	POSTDEC2	Uses contents of FSR2 to address data memory – value of FSR2 post-decremented (not a physical register)								---- ----
FDCh	PREINC2	Uses contents of FSR2 to address data memory – value of FSR2 pre-incremented (not a physical register)								---- ----
FDBh	PLUSW2	Uses contents of FSR2 to address data memory – value of FSR2 pre-incremented (not a physical register) – value of FSR2 offset by W								---- ----
FDAh	FSR2H	—	—	—	—	Indirect Data Memory Address Pointer 2, High Byte				---- 0000
FD9h	FSR2L	Indirect Data Memory Address Pointer 2, Low Byte								xxxx xxxx
FD8h	STATUS	—	—	—	N	OV	Z	DC	C	---x xxxx
FD7h	TMR0H	Timer0 Register, High Byte								0000 0000
FD6h	TMR0L	Timer0 Register, Low Byte								xxxx xxxx
FD5h	T0CON	TMR0ON	T08BIT	T0CS	T0SE	PSA	T0PS<2:0>			1111 1111
FD3h	OSCCON	IDLEN	IRCF<2:0>			OSTS	HFIOFS	SCS<1:0>		0011 q000
FD2h	OSCCON2	PLLRDY	SOSCRUN	—	MFIOSEL	SOSCGO	PRISD	MFIOFS	LFIOFS	00-0 01x0

Legend: x = unknown, u = unchanged, — = unimplemented, q = value depends on condition

Note 1: PIC18(L)F4XK22 devices only.

2: PIC18(L)F2XK22 devices only.

3: PIC18(L)F23/24K22 and PIC18(L)F43/44K22 devices only.

4: PIC18(L)F26K22 and PIC18(L)F46K22 devices only.

Operations on the FSRs with POSTDEC, POSTINC and PREINC affect the entire register pair; that is, rollovers of the FSRnL register from FFh to 00h carry over to the FSRnH register. On the other hand, results of these operations do not change the value of any flags in the STATUS register (e.g., Z, N, OV, etc.).

The PLUSW register can be used to implement a form of indexed addressing in the data memory space. By manipulating the value in the W register, users can reach addresses that are fixed offsets from pointer addresses. In some applications, this can be used to implement some powerful program control structure, such as software stacks, inside of data memory.

5.6.3.3 Operations by FSRs on FSRs

Indirect addressing operations that target other FSRs or virtual registers represent special cases. For example, using an FSR to point to one of the virtual registers will not result in successful operations. As a specific case, assume that FSR0H:FSR0L contains FE7h, the address of INDF1. Attempts to read the value of the INDF1 using INDF0 as an operand will return 00h. Attempts to write to INDF1 using INDF0 as the operand will result in a NOP.

On the other hand, using the virtual registers to write to an FSR pair may not occur as planned. In these cases, the value will be written to the FSR pair but without any incrementing or decrementing. Thus, writing to either the INDF2 or POSTDEC2 register will write the same value to the FSR2H:FSR2L.

Since the FSRs are physical registers mapped in the SFR space, they can be manipulated through all direct operations. Users should proceed cautiously when working on these registers, particularly if their code uses indirect addressing.

Similarly, operations by indirect addressing are generally permitted on all other SFRs. Users should exercise the appropriate caution that they do not inadvertently change settings that might affect the operation of the device.

5.7 Data Memory and the Extended Instruction Set

Enabling the PIC18 extended instruction set (XINST Configuration bit = 1) significantly changes certain aspects of data memory and its addressing. Specifically, the use of the Access Bank for many of the core PIC18 instructions is different; this is due to the introduction of a new addressing mode for the data memory space.

What does not change is just as important. The size of the data memory space is unchanged, as well as its linear addressing. The SFR map remains the same. Core PIC18 instructions can still operate in both Direct and Indirect Addressing mode; inherent and literal instructions do not change at all. Indirect addressing with FSR0 and FSR1 also remain unchanged.

5.7.1 INDEXED ADDRESSING WITH LITERAL OFFSET

Enabling the PIC18 extended instruction set changes the behavior of indirect addressing using the FSR2 register pair within Access RAM. Under the proper conditions, instructions that use the Access Bank – that is, most bit-oriented and byte-oriented instructions – can invoke a form of indexed addressing using an offset specified in the instruction. This special addressing mode is known as Indexed Addressing with Literal Offset, or Indexed Literal Offset mode.

When using the extended instruction set, this addressing mode requires the following:

- The use of the Access Bank is forced (‘a’ = 0) and
- The file address argument is less than or equal to 5Fh.

Under these conditions, the file address of the instruction is not interpreted as the lower byte of an address (used with the BSR in direct addressing), or as an 8-bit address in the Access Bank. Instead, the value is interpreted as an offset value to an Address Pointer, specified by FSR2. The offset and the contents of FSR2 are added to obtain the target address of the operation.

5.7.2 INSTRUCTIONS AFFECTED BY INDEXED LITERAL OFFSET MODE

Any of the core PIC18 instructions that can use direct addressing are potentially affected by the Indexed Literal Offset Addressing mode. This includes all byte-oriented and bit-oriented instructions, or almost one-half of the standard PIC18 instruction set. Instructions that only use Inherent or Literal Addressing modes are unaffected.

Additionally, byte-oriented and bit-oriented instructions are not affected if they do not use the Access Bank (Access RAM bit is ‘1’), or include a file address of 60h or above. Instructions meeting these criteria will continue to execute as before. A comparison of the different possible addressing modes when the extended instruction set is enabled is shown in Figure 5-11.

Those who desire to use byte-oriented or bit-oriented instructions in the Indexed Literal Offset mode should note the changes to assembler syntax for this mode. This is described in more detail in **Section 25.2.1 “Extended Instruction Syntax”**.

EXAMPLE 6-3: WRITING TO FLASH PROGRAM MEMORY

```
                    MOVLW     D'64'                 ; number of bytes in erase block
                    MOVWF     COUNTER
                    MOVLW     BUFFER_ADDR_HIGH      ; point to buffer
                    MOVWF     FSR0H
                    MOVLW     BUFFER_ADDR_LOW
                    MOVWF     FSR0L
                    MOVLW     CODE_ADDR_UPPER       ; Load TBLPTR with the base
                    MOVWF     TBLPTRU               ; address of the memory block
                    MOVLW     CODE_ADDR_HIGH
                    MOVWF     TBLPTRH
                    MOVLW     CODE_ADDR_LOW
                    MOVWF     TBLPTRL
READ_BLOCK
                    TBLRD*+                         ; read into TABLAT, and inc
                    MOVF      TABLAT, W             ; get data
                    MOVWF     POSTINC0              ; store data
                    DECFSZ    COUNTER               ; done?
                    BRA       READ_BLOCK            ; repeat
MODIFY_WORD
                    MOVLW     BUFFER_ADDR_HIGH      ; point to buffer
                    MOVWF     FSR0H
                    MOVLW     BUFFER_ADDR_LOW
                    MOVWF     FSR0L
                    MOVLW     NEW_DATA_LOW          ; update buffer word
                    MOVWF     POSTINC0
                    MOVLW     NEW_DATA_HIGH
                    MOVWF     INDF0
ERASE_BLOCK
                    MOVLW     CODE_ADDR_UPPER       ; load TBLPTR with the base
                    MOVWF     TBLPTRU               ; address of the memory block
                    MOVLW     CODE_ADDR_HIGH
                    MOVWF     TBLPTRH
                    MOVLW     CODE_ADDR_LOW
                    MOVWF     TBLPTRL
                    BSF       EECON1, EEPGD         ; point to Flash program memory
                    BCF       EECON1, CFGS          ; access Flash program memory
                    BSF       EECON1, WREN          ; enable write to memory
                    BSF       EECON1, FREE          ; enable Erase operation
                    BCF       INTCON, GIE           ; disable interrupts
                    MOVLW     55h
Required            MOVWF     EECON2                ; write 55h
Sequence            MOVLW     0AAh
                    MOVWF     EECON2                ; write 0AAh
                    BSF       EECON1, WR            ; start erase (CPU stall)
                    BSF       INTCON, GIE           ; re-enable interrupts
                    TBLRD*-                         ; dummy read decrement
                    MOVLW     BUFFER_ADDR_HIGH      ; point to buffer
                    MOVWF     FSR0H
                    MOVLW     BUFFER_ADDR_LOW
                    MOVWF     FSR0L
WRITE_BUFFER_BACK
                    MOVLW     BlockSize             ; number of bytes in holding register
                    MOVWF     COUNTER
                    MOVLW     D'64'/BlockSize       ; number of write blocks in 64 bytes
                    MOVWF     COUNTER2
WRITE_BYTE_TO_HREGS
                    MOVF      POSTINC0, W           ; get low byte of buffer data
                    MOVWF     TABLAT                ; present data to table latch
                    TBLWT+*                         ; write data, perform a short write
                                                    ; to internal TBLWT holding register.
```

REGISTER 7-1: EECON1: DATA EEPROM CONTROL 1 REGISTER

R/W-x	R/W-x	U-0	R/W-0	R/W-x	R/W-0	R/S-0	R/S-0
EEPGD	CFGS	—	FREE	WRERR	WREN	WR	RD
bit 7							bit 0

Legend:			
R = Readable bit	W = Writable bit		
S = Bit can be set by software, but not cleared		U = Unimplemented bit, read as '0'	
-n = Value at POR	'1' = Bit is set	'0' = Bit is cleared	x = Bit is unknown

bit 7 **EEPGD:** Flash Program or Data EEPROM Memory Select bit
- 1 = Access Flash program memory
- 0 = Access data EEPROM memory

bit 6 **CFGS:** Flash Program/Data EEPROM or Configuration Select bit
- 1 = Access Configuration registers
- 0 = Access Flash program or data EEPROM memory

bit 5 **Unimplemented:** Read as '0'

bit 4 **FREE:** Flash Row (Block) Erase Enable bit
- 1 = Erase the program memory block addressed by TBLPTR on the next WR command (cleared by completion of erase operation)
- 0 = Perform write-only

bit 3 **WRERR:** Flash Program/Data EEPROM Error Flag bit(1)
- 1 = A write operation is prematurely terminated (any Reset during self-timed programming in normal operation, or an improper write attempt)
- 0 = The write operation completed

bit 2 **WREN:** Flash Program/Data EEPROM Write Enable bit
- 1 = Allows write cycles to Flash program/data EEPROM
- 0 = Inhibits write cycles to Flash program/data EEPROM

bit 1 **WR:** Write Control bit
- 1 = Initiates a data EEPROM erase/write cycle or a program memory erase cycle or write cycle. (The operation is self-timed and the bit is cleared by hardware once write is complete. The WR bit can only be set (not cleared) by software.)
- 0 = Write cycle to the EEPROM is complete

bit 0 **RD:** Read Control bit
- 1 = Initiates an EEPROM read (Read takes one cycle. RD is cleared by hardware. The RD bit can only be set (not cleared) by software. RD bit cannot be set when EEPGD = 1 or CFGS = 1.)
- 0 = Does not initiate an EEPROM read

Note 1: When a WRERR occurs, the EEPGD and CFGS bits are not cleared. This allows tracing of the error condition.

7.3 Reading the Data EEPROM Memory

To read a data memory location, the user must write the address to the EEADR register, clear the EEPGD control bit of the EECON1 register and then set control bit, RD. The data is available on the very next instruction cycle; therefore, the EEDATA register can be read by the next instruction. EEDATA will hold this value until another read operation, or until it is written to by the user (during a write operation).

The basic process is shown in Example 7-1.

7.4 Writing to the Data EEPROM Memory

To write an EEPROM data location, the address must first be written to the EEADR register and the data written to the EEDATA register. The sequence in Example 7-2 must be followed to initiate the write cycle.

The write will not begin if this sequence is not exactly followed (write 55h to EECON2, write 0AAh to EECON2, then set WR bit) for each byte. It is strongly recommended that interrupts be disabled during this code segment.

Additionally, the WREN bit in EECON1 must be set to enable writes. This mechanism prevents accidental writes to data EEPROM due to unexpected code execution (i.e., runaway programs). The WREN bit should be kept clear at all times, except when updating the EEPROM. The WREN bit is not cleared by hardware.

After a write sequence has been initiated, EECON1, EEADR and EEDATA cannot be modified. The WR bit will be inhibited from being set unless the WREN bit is set. Both WR and WREN cannot be set with the same instruction.

At the completion of the write cycle, the WR bit is cleared by hardware and the EEPROM Interrupt Flag bit, EEIF, is set. The user may either enable this interrupt or poll this bit. EEIF must be cleared by software.

7.5 Write Verify

Depending on the application, good programming practice may dictate that the value written to the memory should be verified against the original value. This should be used in applications where excessive writes can stress bits near the specification limit.

EXAMPLE 7-1: DATA EEPROM READ

```
        MOVLW   DATA_EE_ADDR   ;
        MOVWF   EEADR          ; Data Memory Address to read
        BCF     EECON1, EEPGD  ; Point to DATA memory
        BCF     EECON1, CFGS   ; Access EEPROM
        BSF     EECON1, RD     ; EEPROM Read
        MOVF    EEDATA, W      ; W = EEDATA
```

EXAMPLE 7-2: DATA EEPROM WRITE

```
                MOVLW   DATA_EE_ADDR_LOW   ;
                MOVWF   EEADR              ; Data Memory Address to write
                MOVLW   DATA_EE_ADDR_HI    ;
                MOVWF   EEADRH             ;
                MOVLW   DATA_EE_DATA       ;
                MOVWF   EEDATA             ; Data Memory Value to write
                BCF     EECON1, EEPGD      ; Point to DATA memory
                BCF     EECON1, CFGS       ; Access EEPROM
                BSF     EECON1, WREN       ; Enable writes
                BCF     INTCON, GIE        ; Disable Interrupts
                MOVLW   55h                ;
Required        MOVWF   EECON2             ; Write 55h
Sequence        MOVLW   0AAh               ;
                MOVWF   EECON2             ; Write 0AAh
                BSF     EECON1, WR         ; Set WR bit to begin write
                BSF     INTCON, GIE        ; Enable Interrupts

                                           ; User code execution
                BCF     EECON1, WREN       ; Disable writes on write complete (EEIF set)
```

TABLE 10-4: PORT PIN FUNCTION PRIORITY (CONTINUED)

Port bit	Port Function Priority by Port Pin				
	PORTA	**PORTB**	**PORTC**	**PORTD(2)**	**PORTE(2)**
5	SRNQ	CCP3(3)	SDO1	P1B	
	C2OUT	P3A(3)	RC5	RD5	
	RA5	P2B(1)(4)			
		RB5			
6	OSC2	PGC	TX1/CK1	TX2/CK2	
	CLKO	TX2/CK2(1)	CCP3(1)(7)	P1C	
	RA6	RB6	P3A(1)(7)	RD6	
		ICDCK	RC6		
7	RA7				
	OSC1	PGD	RX1/DT1	RX2/DT2	
	RA7	RX2/DT2(1)	P3B(1)	P1D	
		RB7	RC7	RD7	
		ICDDT			

Note 1: PIC18(L)F2XK22 devices.
2: PIC18(L)F4XK22 devices.
3: Function default pin.
4: Function default pin (28-pin devices).
5: Function default pin (40/44-pin devices).
6: Function alternate pin.
7: Function alternate pin (28-pin devices).
8: Function alternate pin (40/44-pin devices)

15.6.13 MULTI -MASTER COMMUNICATION, BUS COLLISION AND BUS ARBITRATION

Multi-Master mode support is achieved by bus arbitration. When the master outputs address/data bits onto the SDAx pin, arbitration takes place when the master outputs a '1' on SDAx, by letting SDAx float high and another master asserts a '0'. When the SCLx pin floats high, data should be stable. If the expected data on SDAx is a '1' and the data sampled on the SDAx pin is '0', then a bus collision has taken place. The master will set the Bus Collision Interrupt Flag, BCLxIF, and reset the I^2C port to its Idle state (Figure 15-32).

If a transmit was in progress when the bus collision occurred, the transmission is halted, the BF flag is cleared, the SDAx and SCLx lines are deasserted and the SSPxBUF can be written to. When the user services the bus collision Interrupt Service Routine and if the I^2C bus is free, the user can resume communication by asserting a Start condition.

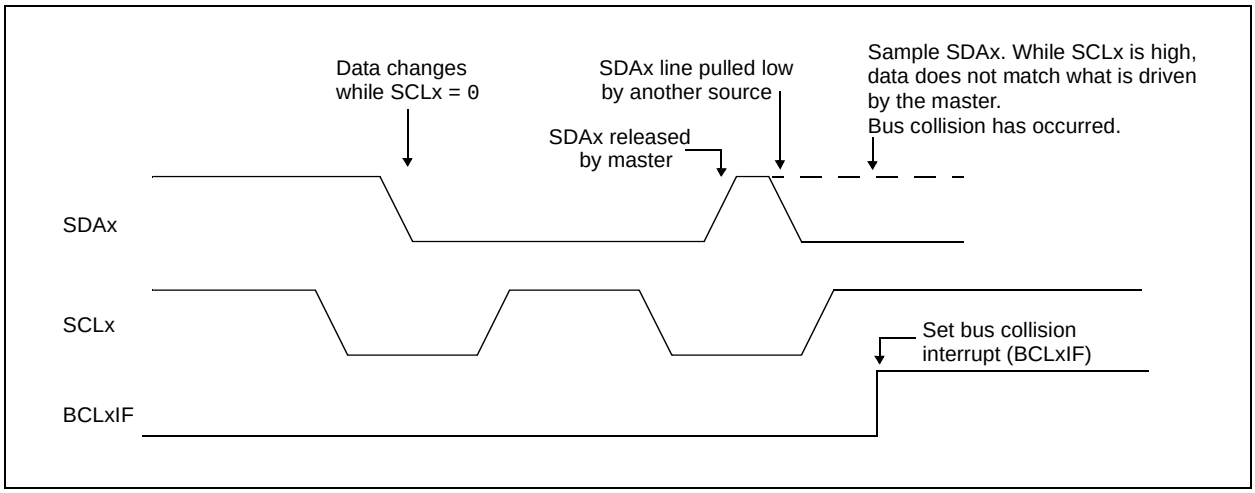
If a Start, Repeated Start, Stop or Acknowledge condition was in progress when the bus collision occurred, the condition is aborted, the SDAx and SCLx lines are deasserted and the respective control bits in the SSPxCON2 register are cleared. When the user services the bus collision Interrupt Service Routine and if the I^2C bus is free, the user can resume communication by asserting a Start condition.

The master will continue to monitor the SDAx and SCLx pins. If a Stop condition occurs, the SSPxIF bit will be set.

A write to the SSPxBUF will start the transmission of data at the first data bit, regardless of where the transmitter left off when the bus collision occurred.

In Multi-Master mode, the interrupt generation on the detection of Start and Stop conditions allows the determination of when the bus is free. Control of the I^2C bus can be taken when the P bit is set in the SSPxSTAT register, or the bus is Idle and the S and P bits are cleared.

FIGURE 15-32: BUS COLLISION TIMING FOR TRANSMIT AND ACKNOWLEDGE



19.4 Measuring Capacitance with the CTMU

There are two separate methods of measuring capacitance with the CTMU. The first is the absolute method, in which the actual capacitance value is desired. The second is the relative method, in which the actual capacitance is not needed, rather an indication of a change in capacitance is required.

19.4.1 ABSOLUTE CAPACITANCE MEASUREMENT

For absolute capacitance measurements, both the current and capacitance calibration steps found in **Section 19.3 "Calibrating the CTMU Module"** should be followed. Capacitance measurements are then performed using the following steps:

1. Initialize the A/D Converter.
2. Initialize the CTMU.
3. Set EDG1STAT.
4. Wait for a fixed delay, *T*.
5. Clear EDG1STAT.
6. Perform an A/D conversion.
7. Calculate the total capacitance, $C_{TOTAL} = (I * T)/V$, where I is known from the current source measurement step (see **Section 19.3.1 "Current Source Calibration"**), T is a fixed delay and V is measured by performing an A/D conversion.
8. Subtract the stray and A/D capacitance (C_{OFFSET} from **Section 19.3.2 "Capacitance Calibration"**) from C_{TOTAL} to determine the measured capacitance.

19.4.2 RELATIVE CHARGE MEASUREMENT

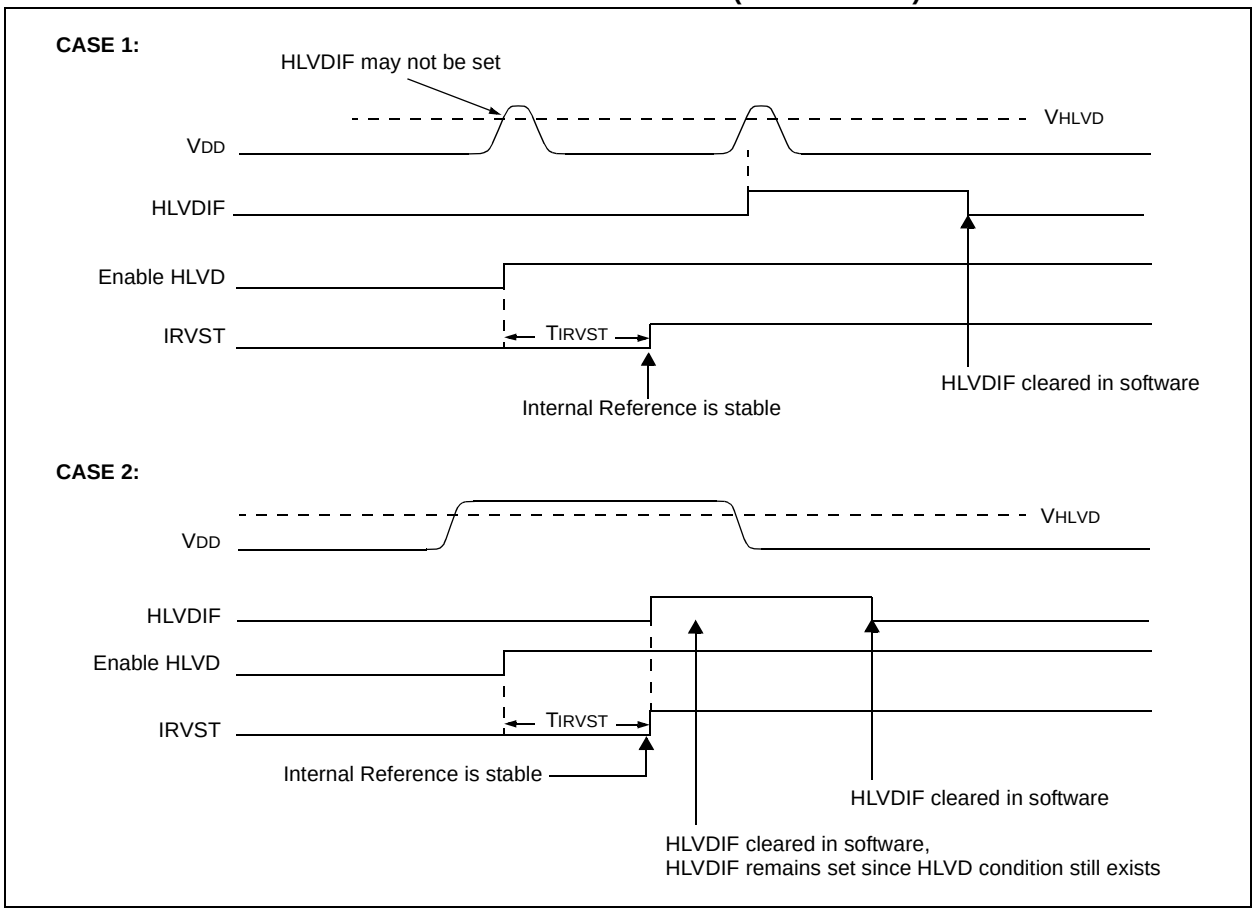
An application may not require precise capacitance measurements. For example, when detecting a valid press of a capacitance-based switch, detecting a relative change of capacitance is of interest. In this type of application, when the switch is open (or not touched), the total capacitance is the capacitance of the combination of the board traces, the A/D Converter, etc. A larger voltage will be measured by the A/D Converter. When the switch is closed (or is touched), the total capacitance is larger due to the addition of the capacitance of the human body to the above listed capacitances, and a smaller voltage will be measured by the A/D Converter.

Detecting capacitance changes is easily accomplished with the CTMU using these steps:

1. Initialize the A/D Converter and the CTMU.
2. Set EDG1STAT.
3. Wait for a fixed delay.
4. Clear EDG1STAT.
5. Perform an A/D conversion.

The voltage measured by performing the A/D conversion is an indication of the relative capacitance. Note that in this case, no calibration of the current source or circuit capacitance measurement is needed. See Example 19-4 for a sample software routine for a capacitive touch switch.

FIGURE 23-3: HIGH-VOLTAGE DETECT OPERATION (VDIRMAG = 1)

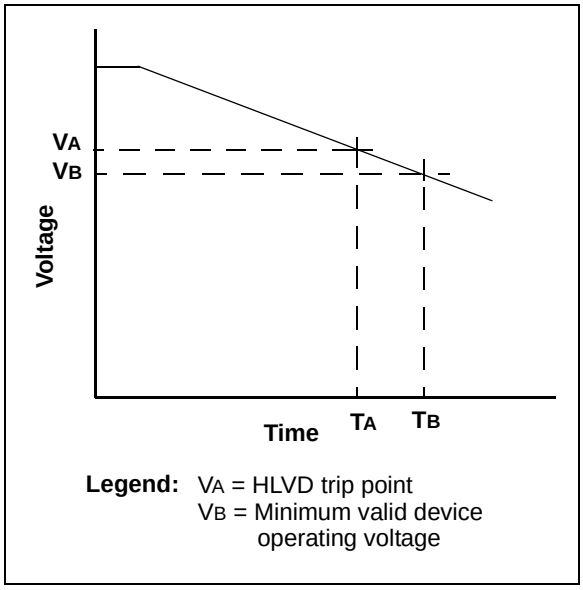


23.6 Applications

In many applications, it is desirable to detect a drop below, or rise above, a particular voltage threshold. For example, the HLVD module could be periodically enabled to detect Universal Serial Bus (USB) attach or detach. This assumes the device is powered by a lower voltage source than the USB when detached. An attach would indicate a high-voltage detect from, for example, 3.3V to 5V (the voltage on USB) and vice versa for a detach. This feature could save a design a few extra components and an attach signal (input pin).

For general battery applications, Figure 23-4 shows a possible voltage curve. Over time, the device voltage decreases. When the device voltage reaches voltage VA, the HLVD logic generates an interrupt at time, TA. The interrupt could cause the execution of an ISR, which would allow the application to perform "house-keeping tasks" and a controlled shutdown before the device voltage exits the valid operating range at TB. This would give the application a time window, represented by the difference between TA and TB, to safely exit.

FIGURE 23-4: TYPICAL LOW-VOLTAGE DETECT APPLICATION



REGISTER 24-3: CONFIG2H: CONFIGURATION REGISTER 2 HIGH

U-0	U-0	R/P-1	R/P-1	R/P-1	R/P-1	R/P-1	R/P-1
—	—	WDTPS<3:0>				WDTEN<1:0>	
bit 7							bit 0

Legend:		
R = Readable bit	P = Programmable bit	U = Unimplemented bit, read as '0'
-n = Value when device is unprogrammed		x = Bit is unknown

bit 7-6 **Unimplemented:** Read as '0'

bit 5-2 **WDTPS<3:0>:** Watchdog Timer Postscale Select bits
1111 = 1:32,768
1110 = 1:16,384
1101 = 1:8,192
1100 = 1:4,096
1011 = 1:2,048
1010 = 1:1,024
1001 = 1:512
1000 = 1:256
0111 = 1:128
0110 = 1:64
0101 = 1:32
0100 = 1:16
0011 = 1:8
0010 = 1:4
0001 = 1:2
0000 = 1:1

bit 1-0 **WDTEN<1:0>:** Watchdog Timer Enable bits
11 = WDT enabled in hardware; SWDTEN bit disabled
10 = WDT controlled by the SWDTEN bit
01 = WDT enabled when device is active, disabled when device is in Sleep; SWDTEN bit disabled
00 = WDT disabled in hardware; SWDTEN bit disabled

TABLE 25-2: PIC18(L)F2X/4XK22 INSTRUCTION SET

Mnemonic, Operands		Description	Cycles	16-Bit Instruction Word				Status Affected	Notes
				MSb			LSb		
BYTE-ORIENTED OPERATIONS									
ADDWF	f, d, a	Add WREG and f	1	0010	01da	ffff	ffff	C, DC, Z, OV, N	1, 2
ADDWFC	f, d, a	Add WREG and CARRY bit to f	1	0010	00da	ffff	ffff	C, DC, Z, OV, N	1, 2
ANDWF	f, d, a	AND WREG with f	1	0001	01da	ffff	ffff	Z, N	1,2
CLRF	f, a	Clear f	1	0110	101a	ffff	ffff	Z	2
COMF	f, d, a	Complement f	1	0001	11da	ffff	ffff	Z, N	1, 2
CPFSEQ	f, a	Compare f with WREG, skip =	1 (2 or 3)	0110	001a	ffff	ffff	None	4
CPFSGT	f, a	Compare f with WREG, skip >	1 (2 or 3)	0110	010a	ffff	ffff	None	4
CPFSLT	f, a	Compare f with WREG, skip <	1 (2 or 3)	0110	000a	ffff	ffff	None	1, 2
DECF	f, d, a	Decrement f	1	0000	01da	ffff	ffff	C, DC, Z, OV, N	1, 2, 3, 4
DECFSZ	f, d, a	Decrement f, Skip if 0	1 (2 or 3)	0010	11da	ffff	ffff	None	1, 2, 3, 4
DCFSNZ	f, d, a	Decrement f, Skip if Not 0	1 (2 or 3)	0100	11da	ffff	ffff	None	1, 2
INCF	f, d, a	Increment f	1	0010	10da	ffff	ffff	C, DC, Z, OV, N	1, 2, 3, 4
INCFSZ	f, d, a	Increment f, Skip if 0	1 (2 or 3)	0011	11da	ffff	ffff	None	4
INFSNZ	f, d, a	Increment f, Skip if Not 0	1 (2 or 3)	0100	10da	ffff	ffff	None	1, 2
IORWF	f, d, a	Inclusive OR WREG with f	1	0001	00da	ffff	ffff	Z, N	1, 2
MOVF	f, d, a	Move f	1	0101	00da	ffff	ffff	Z, N	1
MOVFF	f_s, f_d	Move f_s (source) to 1st word f_d (destination) 2nd word	2	1100 1111	ffff ffff	ffff ffff	ffff ffff	None	
MOVWF	f, a	Move WREG to f	1	0110	111a	ffff	ffff	None	
MULWF	f, a	Multiply WREG with f	1	0000	001a	ffff	ffff	None	1, 2
NEGF	f, a	Negate f	1	0110	110a	ffff	ffff	C, DC, Z, OV, N	
RLCF	f, d, a	Rotate Left f through Carry	1	0011	01da	ffff	ffff	C, Z, N	1, 2
RLNCF	f, d, a	Rotate Left f (No Carry)	1	0100	01da	ffff	ffff	Z, N	
RRCF	f, d, a	Rotate Right f through Carry	1	0011	00da	ffff	ffff	C, Z, N	
RRNCF	f, d, a	Rotate Right f (No Carry)	1	0100	00da	ffff	ffff	Z, N	
SETF	f, a	Set f	1	0110	100a	ffff	ffff	None	1, 2
SUBFWB	f, d, a	Subtract f from WREG with borrow	1	0101	01da	ffff	ffff	C, DC, Z, OV, N	
SUBWF	f, d, a	Subtract WREG from f	1	0101	11da	ffff	ffff	C, DC, Z, OV, N	1, 2
SUBWFB	f, d, a	Subtract WREG from f with borrow	1	0101	10da	ffff	ffff	C, DC, Z, OV, N	
SWAPF	f, d, a	Swap nibbles in f	1	0011	10da	ffff	ffff	None	4
TSTFSZ	f, a	Test f, skip if 0	1 (2 or 3)	0110	011a	ffff	ffff	None	1, 2
XORWF	f, d, a	Exclusive OR WREG with f	1	0001	10da	ffff	ffff	Z, N	

Note 1: When a PORT register is modified as a function of itself (e.g., `MOVF PORTB, 1, 0`), the value used will be that value present on the pins themselves. For example, if the data latch is '1' for a pin configured as input and is driven low by an external device, the data will be written back with a '0'.

2: If this instruction is executed on the TMR0 register (and where applicable, 'd' = 1), the prescaler will be cleared if assigned.

3: If Program Counter (PC) is modified or a conditional test is true, the instruction requires two cycles. The second cycle is executed as a NOP.

4: Some instructions are two-word instructions. The second word of these instructions will be executed as a NOP unless the first word of the instruction retrieves the information embedded in these 16 bits. This ensures that all program memory locations have a valid instruction.

27.4 DC Characteristics: RC Idle Supply Current, PIC18(L)F2X/4XK22 (Continued)

PIC18LF2X/4XK22		Standard Operating Conditions (unless otherwise stated) Operating temperature -40°C ≤ TA ≤ +125°C					
PIC18F2X/4XK22		**Standard Operating Conditions (unless otherwise stated)** Operating temperature -40°C ≤ TA ≤ +125°C					
Param No.	**Device Characteristics**	**Typ**	**Max**	**Units**	**Conditions**		
D055		0.25	0.40	mA	-40°C to +125°C	VDD = 1.8V	FOSC = 1 MHz (**RC_IDLE** mode, HFINTOSC source)
D056		0.35	0.50	mA	-40°C to +125°C	VDD = 3.0V	
D057		0.30	0.45	mA	-40°C to +125°C	VDD = 2.3V	FOSC = 1 MHz (**RC_IDLE** mode, HFINTOSC source)
D058		0.40	0.50	mA	-40°C to +125°C	VDD = 3.0V	
D059		0.45	0.60	mA	-40°C to +125°C	VDD = 5.0V	
D060		0.50	0.7	mA	-40°C to +125°C	VDD = 1.8V	FOSC = 16 MHz (**RC_IDLE** mode, HFINTOSC source)
D061		0.80	1.1	mA	-40°C to +125°C	VDD = 3.0V	
D062		0.65	1.0	mA	-40°C to +125°C	VDD = 2.3V	FOSC = 16 MHz (**RC_IDLE** mode, HFINTOSC source)
D063		0.80	1.1	mA	-40°C to +125°C	VDD = 3.0V	
D064		0.95	1.2	mA	-40°C to +125°C	VDD = 5.0V	
D066		2.5	3.5	mA	-40°C to +125°C	VDD = 3.0V	FOSC = 64 MHz (**RC_IDLE** mode, HFINTOSC + PLL source)
D068		2.5	3.5	mA	-40°C to +125°C	VDD = 3.0V	FOSC = 64 MHz (**RC_IDLE** mode, HFINTOSC + PLL source)
D069		3.0	4.5	mA	-40°C to +125°C	VDD = 5.0V	

Note 1: The supply current is mainly a function of operating voltage, frequency and mode. Other factors, such as I/O pin loading and switching rate, oscillator type and circuit, internal code execution pattern and temperature, also have an impact on the current consumption.
Test condition: All Peripheral Module Control bits in PMD0, PMD1 and PMD2 set to '1'.

2: The test conditions for all IDD measurements in active operation mode are:
All I/O pins set as outputs driven to Vss;
$\overline{MCLR}$ = VDD;
OSC1 = external square wave, from rail-to-rail (PRI_RUN and PRI_IDLE only).

27.11 AC (Timing) Characteristics

27.11.1 TIMING PARAMETER SYMBOLOGY

The timing parameter symbols have been created using one of the following formats:

1. TppS2ppS
2. TppS
3. TCC:ST (I^2C specifications only)
4. Ts (I^2C specifications only)

T			
F	Frequency	T	Time

Lowercase letters (pp) and their meanings:

pp			
cc	CCP1	osc	OSC1
ck	CLKOUT	rd	$\overline{RD}$
cs	$\overline{CS}$	rw	$\overline{RD}$ or $\overline{WR}$
di	SDI	sc	SCK
do	SDO	ss	$\overline{SS}$
dt	Data in	t0	T0CKI
io	I/O port	t1	T13CKI
mc	$\overline{MCLR}$	wr	$\overline{WR}$

Uppercase letters and their meanings:

S			
F	Fall	P	Period
H	High	R	Rise
I	Invalid (High-impedance)	V	Valid
L	Low	Z	High-impedance
I^2C only			
AA	output access	High	High
BUF	Bus free	Low	Low

TCC:ST (I^2C specifications only)

CC			
HD	Hold	SU	Setup
ST			
DAT	DATA input hold	STO	Stop condition
STA	Start condition		

27.11.2 TIMING CONDITIONS

The temperature and voltages specified in Table 27-6 apply to all timing specifications unless otherwise noted. Figure 27-6 specifies the load conditions for the timing specifications.

TABLE 27-6: TEMPERATURE AND VOLTAGE SPECIFICATIONS – AC

AC CHARACTERISTICS	**Standard Operating Conditions (unless otherwise stated)** Operating temperature -40°C ≤ TA ≤ +125°C Operating voltage VDD range as described in **Section 27.1 "DC Characteristics: Supply Voltage, PIC18(L)F2X/4XK22"** and **Section 27.9 "Memory Programming Requirements"**.

FIGURE 27-6: LOAD CONDITIONS FOR DEVICE TIMING SPECIFICATIONS

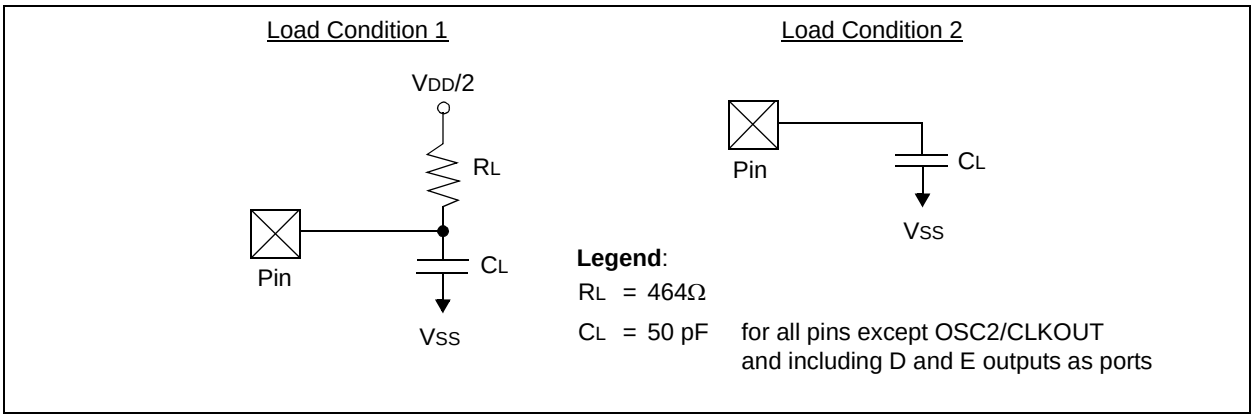
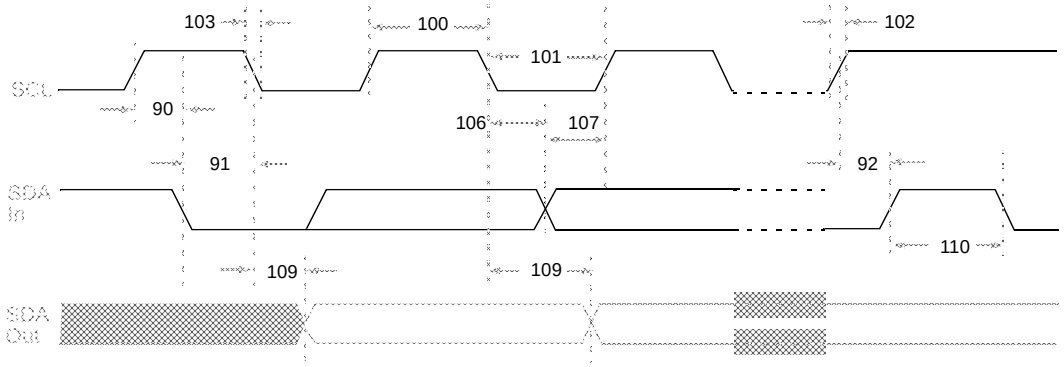


TABLE 27-15: I²C BUS START/STOP BITS REQUIREMENTS (SLAVE MODE)

Param. No.	Symbol	Characteristic		Min	Max	Units	Conditions
90	TSU:STA	Start Condition Setup Time	100 kHz mode	4700	—	ns	Only relevant for Repeated Start condition
			400 kHz mode	600	—		
91	THD:STA	Start Condition Hold Time	100 kHz mode	4000	—	ns	After this period, the first clock pulse is generated
			400 kHz mode	600	—		
92	TSU:STO	Stop Condition Setup Time	100 kHz mode	4700	—	ns	
			400 kHz mode	600	—		
93	THD:STO	Stop Condition Hold Time	100 kHz mode	4000	—	ns	
			400 kHz mode	600	—		

FIGURE 27-18: I²C BUS DATA TIMING



Note: Refer to Figure 27-6 for load conditions.

FIGURE 28-98: PIC18F2X/4XK22 TYPICAL FIXED VOLTAGE REFERENCE 4x OUTPUT

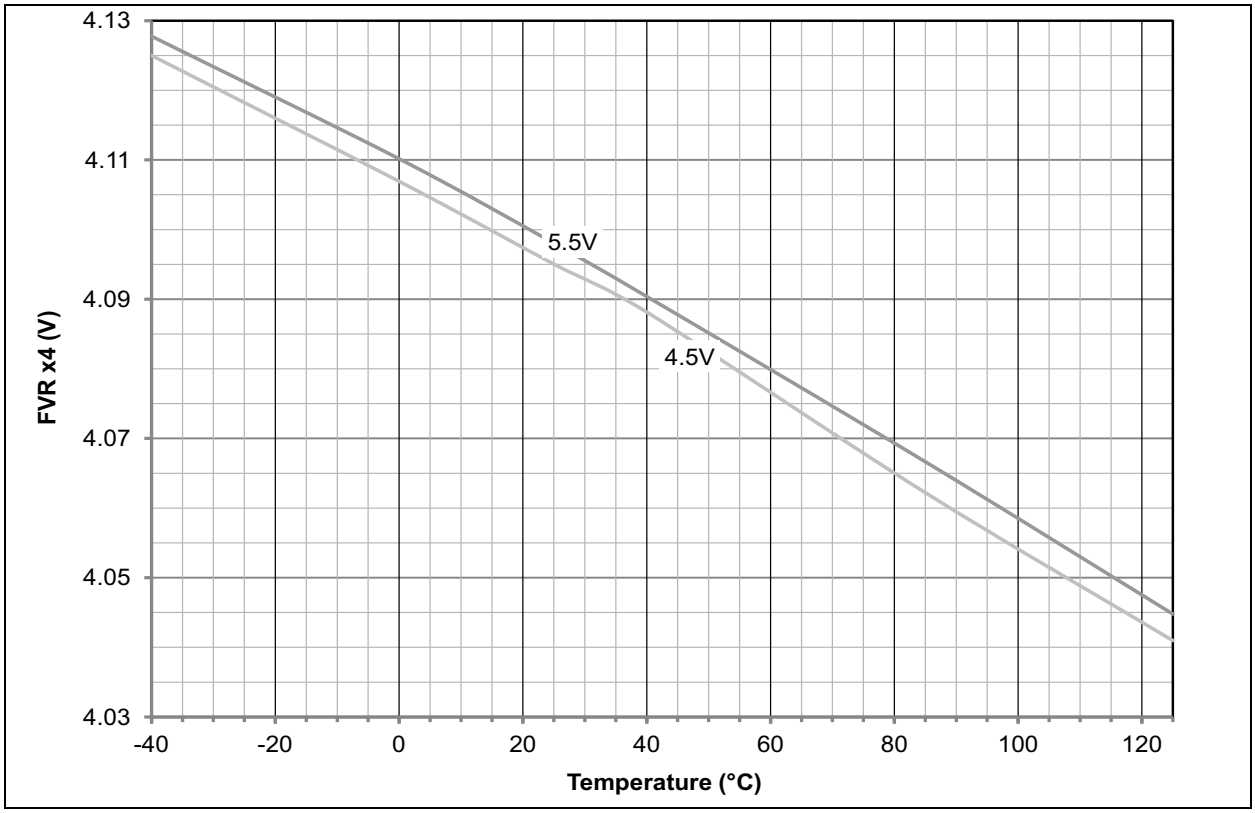
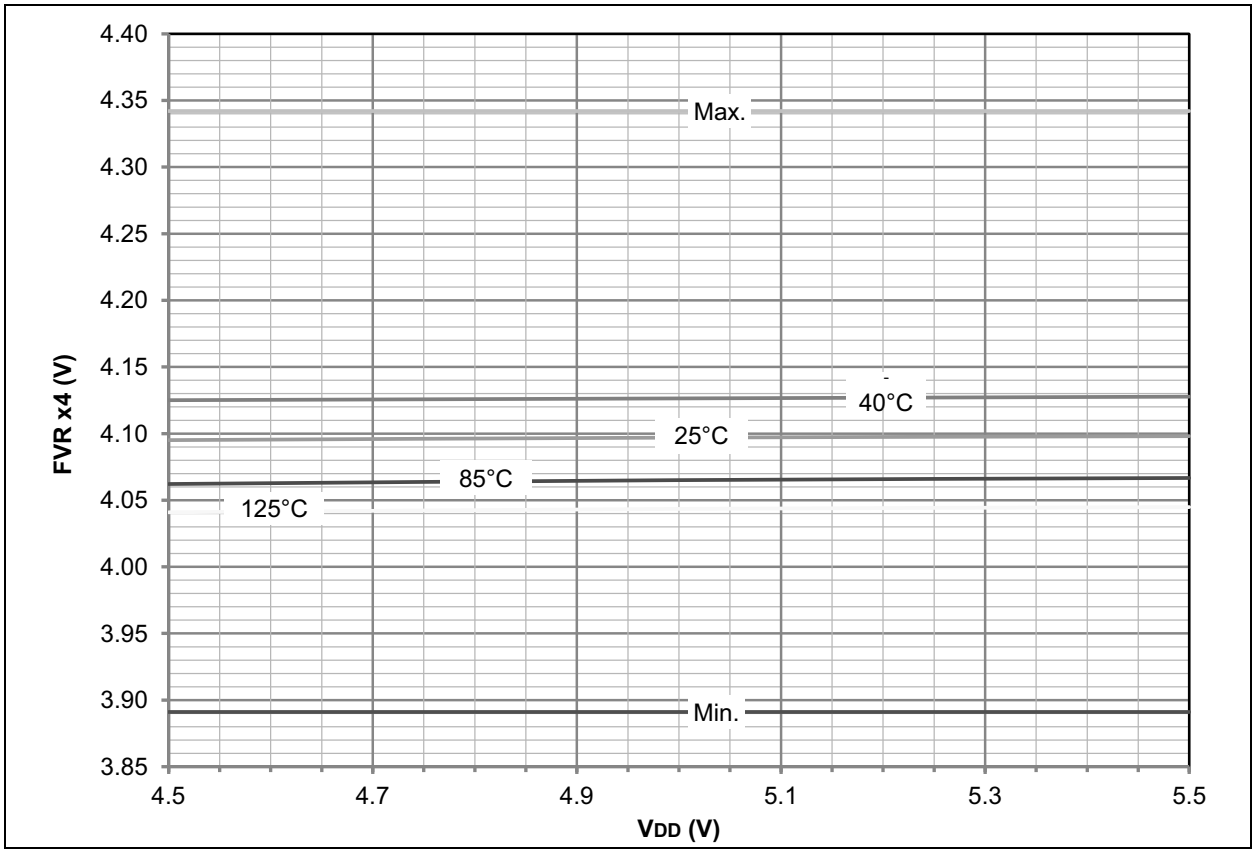


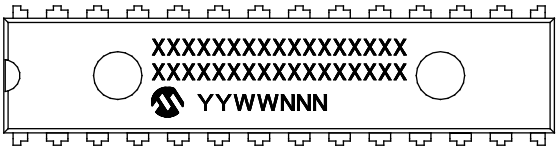
FIGURE 28-99: PIC18F2X/4XK22 TYPICAL FIXED VOLTAGE REFERENCE 4x OUTPUT



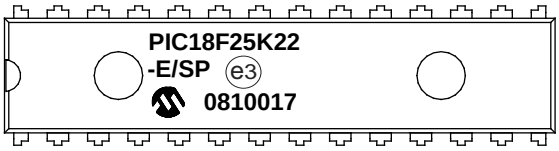
29.0 PACKAGING INFORMATION

29.1 Package Marking Information

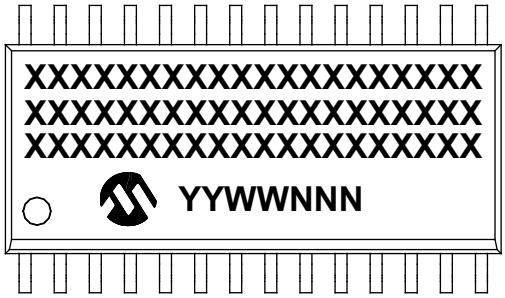
28-Lead SPDIP (.300”)



Example

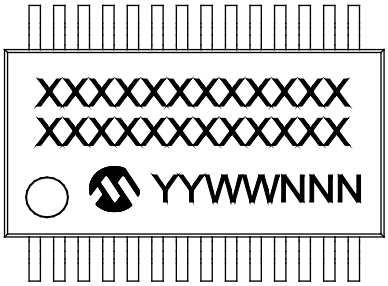


28-Lead SOIC (7.50 mm)

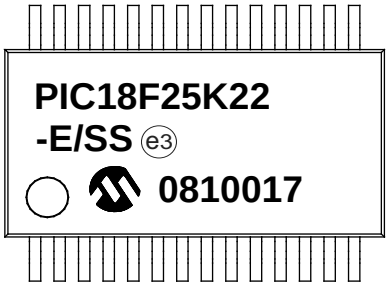


Example

28-Lead SSOP (5.30 mm)



Example



Legend:	XX...X	Customer-specific information or Microchip part number
	Y	Year code (last digit of calendar year)
	YY	Year code (last 2 digits of calendar year)
	WW	Week code (week of January 1 is week ‘01’)
	NNN	Alphanumeric traceability code
	(e3)	Pb-free JEDEC® designator for Matte Tin (Sn)
	*	This package is Pb-free. The Pb-free JEDEC designator ((e3)) can be found on the outer packaging for this package.

Note: In the event the full Microchip part number cannot be marked on one line, it will be carried over to the next line, thus limiting the number of available characters for customer-specific information.